


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Ashjaee et al.	Group Art Unit: Not yet assigned
Serial No.: Not yet assigned	Examiner: Not yet assigned
Filed: February 25, 2004	Docket: NT-261C-US
Title: Method Of Sealing Wafer Backside For Full-Face Processing	CERTIFICATE OF MAILING I hereby certify that this correspondence is being deposited with the US Postal Service as Express Mail Post Office to Addressee with Express Mailing Label No. <u>ER 619647606 US</u> to the address Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22213 on February 25, 2004.
	Signed:  Daniel Hopon

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Applicants submit information herewith to comply with the obligations set forth in 37 CFR §1.56. This submission is not an admission that any of the documents are prior art or otherwise relevant to the subject application.

This IDS is submitted:

- ☒ with a filed patent application or within 3 months of the US application filing date;
- ☐ before the mailing of a first office action on the merits;
- ☐ after the first office action, but prior to a final rejection or notice of allowance, and is accompanied by the fee set forth in 37 CFR §1.17(p) or a certification set forth below; or
- ☐ after a final rejection or notice of allowance, and is accompanied by the fee set forth in 37 CFR §1.17(p) and a certification set forth below, where this submission is a petition requesting consideration of this IDS.

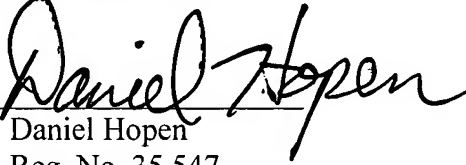
If identified above, Applicant certifies that:

- ☐ the information was first cited in a communication from a foreign patent office in a counterpart foreign application less than 3 months prior to this IDS; or

[] to the knowledge of the person signing this certification after making reasonable inquiry, the information was not known to any individuals designated in 37 CFR §1.56 more than 3 months prior to this IDS.

If any matters can be resolved by telephone, Applicant requests that the Patent and Trademark Office call the Applicant at the telephone number listed below.

Respectfully submitted,

By: 
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In re application of: Ashjaee et al.	Group Art Unit: Not yet assigned
Serial No.: Not yet assigned	Examiner: Not yet assigned
Filed: February 25, 2004	Docket: NT-261C1-US
Title: Method Of Sealing Wafer Backside For Full-Face Processing	

INFORMATION DISCLOSURE STATEMENT

US PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant	
	AA	6,290,577	Sep., 2001	Shendon et al.	In serial No. 09/910,686
	AB	6,228,233	May, 2001	Lakshmikanthan et al.	In serial No. 09/910,686
	AC	6,149,727	Nov., 2000	Yoshioka et al.	Copy Enclosed
	AD	6,024,630	Feb., 2000	Shendon et al.	Copy Enclosed
	AE	5,797,789	Aug., 1998	Tanaka et al.	In serial No. 09/910,686
	AF	5,795,215	Aug., 1998	Guthrie et al.	Copy Enclosed
	AG	5,635,083	June, 1997	Breivogel et al.	Copy Enclosed
	AH	5,374,594	Dec., 1994	Van De Ven et al.	Copy Enclosed

FOREIGN PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant		Translation

OTHER DOCUMENTS

Examiner Initials	Cite No.			Translation

Examiner Signature		Date Considered	
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